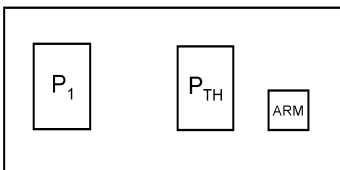


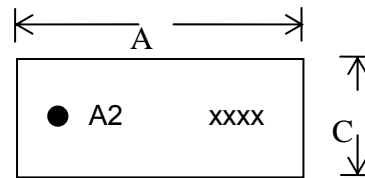
## Specification Status: Preliminary

### PIN CONFIGURATION AND DESCRIPTION:

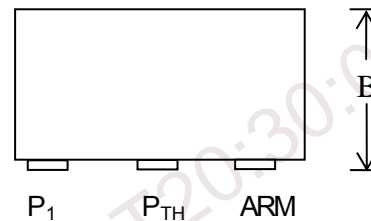
#### Pin Configuration (Bottom View of Device)



#### (Top View of Device)



#### (Side View of Device)



Note:  
A2 is product code  
xxxx is Batch Code  
P1 indicated by inmolded mark

**TABLE 1. DIMENSIONS:**

	A		B		C	
	MIN	MAX	MIN	MAX	MIN	MAX
mm	11.60	12.00	6.00	6.35	5.25	5.50
in:	(0.46)	(0.47)	(0.24)	(0.25)	(0.21)	(0.22)

**TABLE 2. ABSOLUTE MAX RATINGS:**

Absolute Max Ratings		Max	Units
Max DC Open Voltage <sup>1</sup>		32	V <sub>DC</sub>
Max DC Interrupt Current <sup>1</sup>	@ 16 V <sub>DC</sub>	200	A
	@ 24 V <sub>DC</sub>	130	
	@ 32 V <sub>DC</sub>	100	
ESD rating (Human Body Model)		25	KV
Max Reflow Temperature (pre-arming)		260	°C
Operating temperature limits, post-arming, non-opening		-55 +175	°C

1. Performance capability at these conditions can be influenced by board design. Performance should be verified in the user's system.

**TABLE 3. PERFORMANCE CHARACTERISTICS (Typical unless otherwise specified):**

Resistance and Open Characteristics P <sub>1</sub> to P <sub>TH</sub>		Min	Typ	Max	Units
R <sub>PP</sub> (Resistance from P <sub>1</sub> to P <sub>TH</sub> )	@ 23+/-3°C @ 175+/-3°C		0.6 0.8	0.8 1.0	mΩ
Operating Voltage			32		V <sub>DC</sub>
Open Temperature, post-arming	I <sub>PP</sub> = 0	200	205	210	°C
Thermal Resistance: Junction to Ambient <sup>2</sup>	See note 2		150		°C/W
Thermal Resistance: Junction to Case	Case = P <sub>TH</sub> pad		0.5		°C/W
Installation dependent Operating Current, post-arming <sup>2,3</sup>	@ 23+/-3°C @ 100+/-3°C @ 175+/-3°C	32	34 28 10		A
Moisture Sensitivity Level Rating <sup>4</sup>			1		

2. Results obtained on 44.4mm x 57.2mm x 1.6mm single layer FR4 boards with 2oz Cu traces, a 645 sq. mm, 2oz Cu heat spreader connected to the P<sub>TH</sub> pad, and a 387 sq. mm Cu heat spreader connected to the P<sub>1</sub> pad of the RTP device. (See RTP test board drawing in the RTP Datasheet). Results are highly installation-dependent. Users should confirm for their own applications.
3. Operating current is measured on the RTP test board (see the RTP Datasheet) at the specified temperature. It is a highly installation dependent value. Users should confirm for their own applications.
4. As per JEDEC J-STD-020C

**TABLE 4. ARMING CHARACTERISTICS:**

Arming Characteristics ARM		Min	Typ	Max	Units
Arming Type		Electronically Armed			
R <sub>ARM</sub> (Resistance from ARM to P <sub>1</sub> or P <sub>TH</sub> )	Pre-Arming		300		mΩ
	Post-Arming	10			KΩ
Arming Current (I <sub>ARM</sub> ) <sup>5</sup>	@ 23 +/-3°C	2		5	A
Arming Time (@23 +/-3°C) <sup>5</sup>	@ 2A		0.20		Sec
	@ 5A		0.02		

5. Results obtained on 44.4mm x 57.2mm x 1.6mm single layer FR4 boards with 2oz, Cu traces, a 645 sq. mm 2oz Cu heat spreader connected to the P<sub>TH</sub> pad, and a 387 sq. mm Cu heat spreader connected to the P<sub>1</sub> pad of the RTP device. (See RTP test board drawing in the RTP Datasheet.) Results are highly installation dependent. Users should confirm for their own applications.